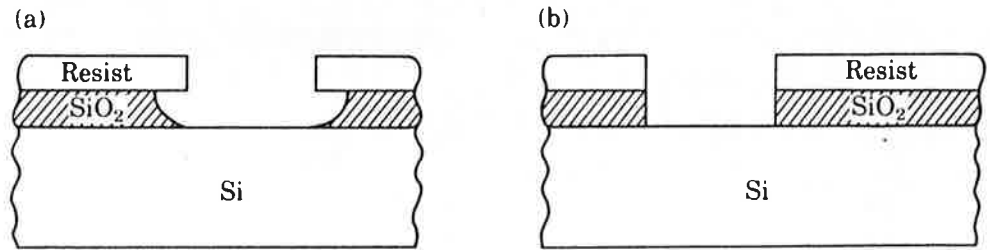


FIGURE 34.7

Etching profiles resulting from (a) isotropic wet etching and (b) anisotropic dry etching. *Source:* R. C. Jaeger.



Wet etching is isotropic therefore permits undercut as shown in (a).

Plasma etching is anisotropic so allows minimal undercutting as in (b).